

CLEANING FLUX, CLEANING SOLDER PASTE, AND SOLDER JOINT**ABSTRACT**

5 A purpose is to provide a cleaning flux that does not inhibit a function for removing a metal oxide film but suppresses volatilization by heating during soldering.

 The cleaning flux contains as a solvent 60-98% by weight of one or both of an alkylene oxide-resorcinol copolymer and an ethylene oxide-propylene oxide condensation-added alkylene diamine wherein an addition amount of the alkylene oxide-resorcinol copolymer is within a range of 0-98% by
10 weight and the addition amount of the ethylene oxide-propylene oxide condensation-added alkylene diamine is within the range of 0-98% by weight; and further one or both of an organic acid and a halogen compound wherein the addition amount of the organic acid is within the range of 0-18% by weight and the addition amount of the halogen compound is within the range of 0-4% by weight.

15 [No suitable figure]